

STN	Integrácia softvérového nástroja (FDI)® Časť 103-1: Profily PROFIBUS	STN EN IEC 62769-103-1 18 4012
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Field Device Integration (FDI)- Part 103-1: Profiles - PROFIBUS

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 07/23

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English Version

**Field Device Integration (FDI)[®] - Part 103-1: Profiles -
PROFIBUS
(IEC 62769-103-1:2023)**

Intégration des appareils de terrain (FDI)[®] - Partie 103-1:
Profils - PROFIBUS
(IEC 62769-103-1:2023)

Feldgeräteintegration (FDI) - Teil 103-1: Profile -
PROFIBUS
(IEC 62769-103-1:2023)

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EN IEC 62769-103-1:2023 (E)**European foreword**

The text of document 65E/862/CDV, future edition 3 of IEC 62769-103-1, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-103-1:2023.

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IEC 62769 (series) NOTE Approved as EN IEC 62769 (series)

IEC 62769-8 NOTE Approved as EN IEC 62769-8

Annex ZA (normative)

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NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

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<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61784-1	-	Industrial communication networks - Profiles Part 1: Fieldbus profiles	EN IEC 61784-1	-
IEC 61804	series	Devices and integration in enterprise systems - Function blocks (FB) for process control and electronic device description language (EDDL)	EN IEC 61804	series
IEC 62541-100	2015	OPC Unified Architecture - Part 100: Device Interface	EN 62541-100	2015
IEC 62769-2	-	Field Device Integration (FDI®) - Part 2: Client	EN IEC 62769-2	-
IEC 62769-4	-	Field Device Integration (FDI®) - Part 4: FDI Packages	EN IEC 62769-4	-
IEC 62769-5	-	Field Device Integration (FDI®) - Part 5: FDI Information Model	EN IEC 62769-5	-
IEC 62769-7	-	Field Device Integration (FDI®) - Part 7: Communication Devices	EN IEC 62769-7	-
PI Order No.: 2.122	2008	Specification for PROFIBUS - Device Description and Device Integration - Volume 1: GSD, V5.1, July 2008: GSD	-	-



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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field Device Integration (FDI)[®] –
Part 103-1: Profiles – PROFIBUS**

**Intégration des appareils de terrain (FDI)[®] –
Partie 103-1: Profils – PROFIBUS**





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IEC Secretariat
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
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IEC 62769-103-1

Edition 3.0 2023-04

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field Device Integration (FDI)[®] –
Part 103-1: Profiles – PROFIBUS**

**Intégration des appareils de terrain (FDI)[®] –
Partie 103-1: Profils – PROFIBUS**

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FIELD DEVICE INTEGRATION (FDI®) –

Part 103-1: Profiles – PROFIBUS

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IEC 62769-103-1 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2020. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added DEVICE_ID to the ProfibusIdentificationType and namespace to Annex A and Annex B;
- b) added mapping from PB standard parameters to PA DIM.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/862/CDV	65E/919/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 62769 series, published under the general title *Field device integration (FDI[®])*, can be found on the IEC website.

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FIELD DEVICE INTEGRATION (FDI®) –**Part 103-1: Profiles – PROFIBUS****1 Scope**

This part of IEC 62769 specifies an FDI^{®1} profile of IEC 62769 for IEC 61784-1_CP 3/1 (PROFIBUS DP)² and IEC 61784-1_CP3/2 (PROFIBUS PA).

2 Normative references

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IEC 61784-1, *Industrial communication networks – Profiles – Part 1: Fieldbus profiles*

IEC 61804 (all parts), *Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL)*

IEC 62541-100:2015, *OPC Unified Architecture – Part 100: OPC UA for Devices*

IEC 62769-2, *Field device integration (FDI[®]) – Part 2: Client*

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PI Order No.: 2.122:2008, *Specification for PROFIBUS – Device Description and Device Integration – Volume 1: GSD, V5.1, July 2008: GSD*; available at <www.PROFIBUS.com>

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